

-40V P-Channel Power MOSFET

• **General Description**

It combines trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

• **Features**

- AEC-Q101 Qualified
- Low $R_{DS(ON)}$ to minimize conductive loss
- High GOX reliability
- Low Thermal resistance

• **Application**

- BLDC Motor driver
- DC-DC
- Load switch

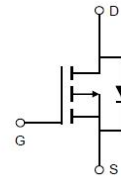
• **Ordering Information:**

Part NO.	ZMA040P04G
Marking	ZM040P04
Packing Information	REEL TAPE
Basic ordering unit (pcs)	2500

• **Absolute Maximum Ratings** ($T_C=25^\circ\text{C}$)

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	V_{DS}		-40	V
Gate-Source Voltage ^①	V_{GS}		± 20	V
Continuous Drain Current	I_D	$T_C=25^\circ\text{C}$	-160	A
	I_D	$T_C=75^\circ\text{C}$	-128	A
	I_D	$T_C=100^\circ\text{C}$	-111	A
Pulsed Drain Current	I_{DM}	Pulsed; $t_p \leq 10 \mu\text{s}$; $T_{mb} = 25^\circ\text{C}$;	-640	A
Total Power Dissipation	P_D	$T_C=25^\circ\text{C}$	188	W
Total Power Dissipation	P_D	$T_A=25^\circ\text{C}$	4.3	W
Operating Junction Temperature	T_J		-55 to +175	$^\circ\text{C}$
Storage Temperature	T_{STG}		-55 to +175	$^\circ\text{C}$
Single Pulse Avalanche Energy	E_{AS}	$L=0.1\text{mH}$, $V_{GS}=-10\text{V}$, $R_g=25\Omega$,	240	mJ
		$L=0.5\text{mH}$, $V_{GS}=-10\text{V}$, $R_g=25\Omega$,	504	mJ
ESD Level (HBM)	CLASS 2			

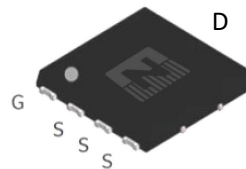
• **Product Summary**



$$V_{DS} = -40\text{V}$$

$$R_{DS(ON)} = 3.8\text{m}\Omega$$

$$I_D = -160\text{A}$$



DFN8*8



•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}		-	0.8	°C/W
Thermal resistance, junction-ambient ^②	R_{thJA}		-	35	°C/W
Soldering temperature	T_{sold}		-	260	°C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-40			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.3	-1.8	-2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{GS}=0V, V_{DS}=-40V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-40A$		3.8	4.6	m Ω
		$V_{GS}=-4.5V, I_D=-25A$		6.0	7.8	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=-5V, I_{SD}=-20A$		28		S
Diode Forward Voltage	V_{FSD}	$V_{GS}=0V, I_{SD}=-40A$			1.3	V

•Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C_{iss}	$f=1MHz, V_{DS}=-25V$	-	10120	-	pF
Output capacitance	C_{oss}		-	762	-	
Reverse transfer capacitance	C_{rss}		-	646	-	
Gate Resistance	R_g	$f=1MHz$	-	3		Ω
Total gate charge	Q_g	$V_{DD}=-15V, I_D=-20A, V_{GS}=-10V$	-	172	-	nC
	$Q_g(-4.5v)$		-	83	-	
Gate - Source charge	Q_{gs}		-	21	-	
Gate - Drain charge	Q_{gd}		-	32	-	
Turn-ON Delay time	$t_{D(on)}$	$V_{GS}=-10V, V_{DS}=-15V, R_G=3.3\Omega, I_D=-20A$	-	18	-	ns
Turn-ON Rise time	t_r		-	27	-	ns
Turn-Off Delay time	$t_{D(off)}$		-	105	-	ns
Turn-Off Fall time	t_f		-	45	-	ns

Fig.1 Gate-Charge Characteristics

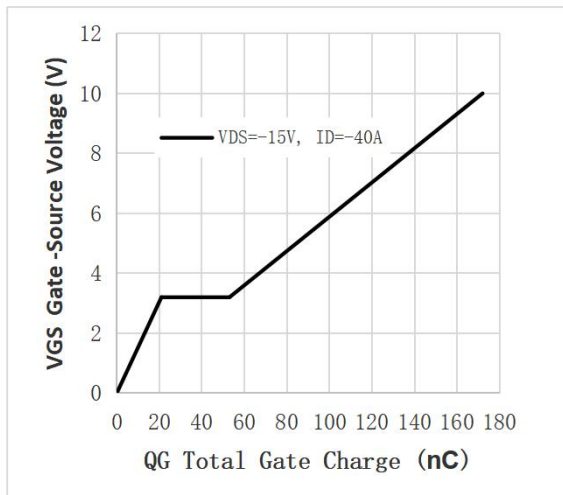


Fig.2 Capacitance Characteristics

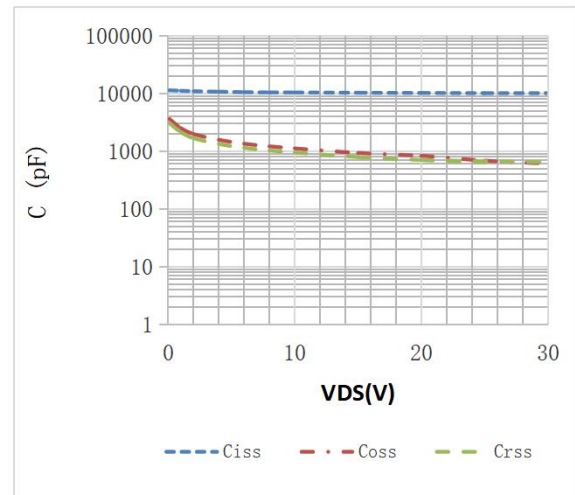


Fig.3 Power Dissipation

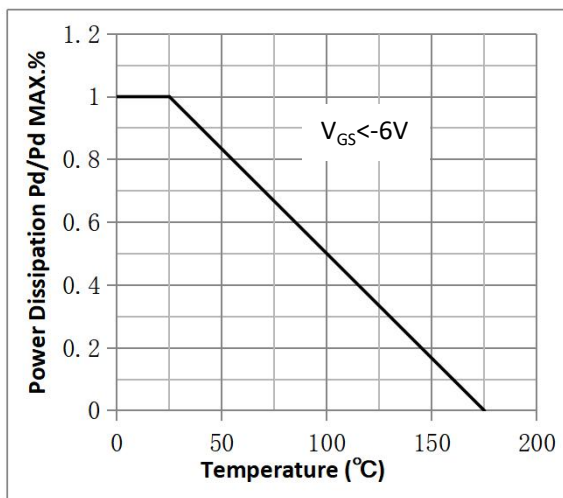


Fig.4 Typical output Characteristics

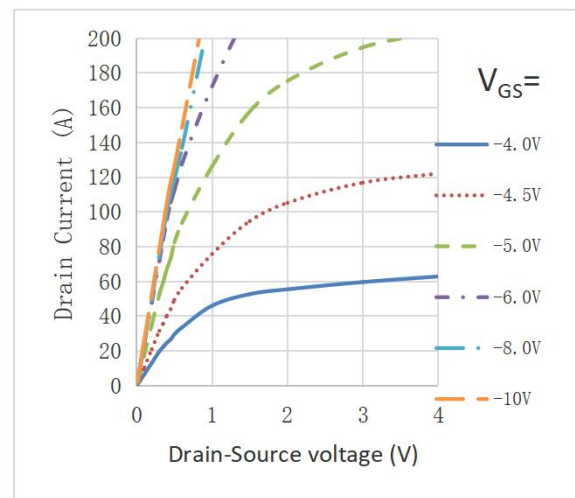


Fig.5 Threshold Voltage V.S Junction Temperature

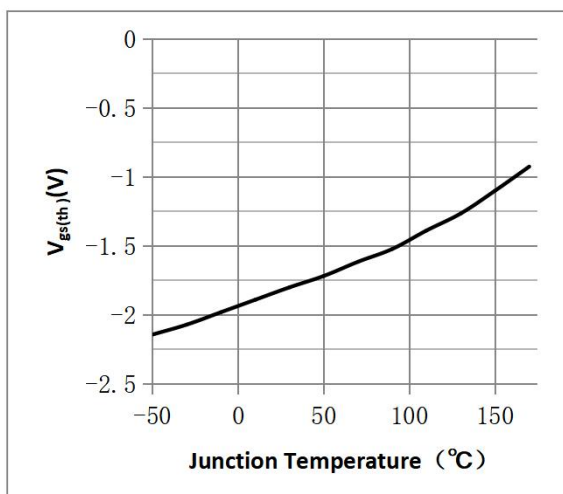


Fig.6 Resistance V.S Drain Current

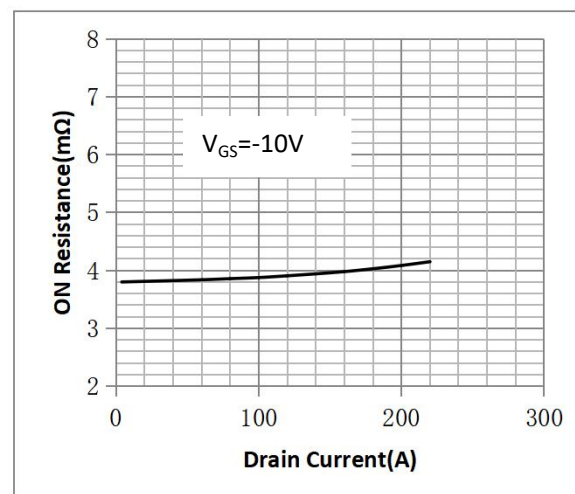


Fig.7 On-Resistance VS Gate Source Voltage

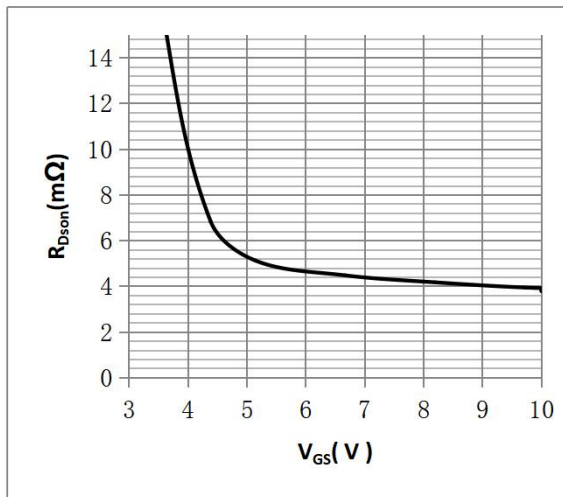


Fig.8 On-Resistance V.S Junction Temperature

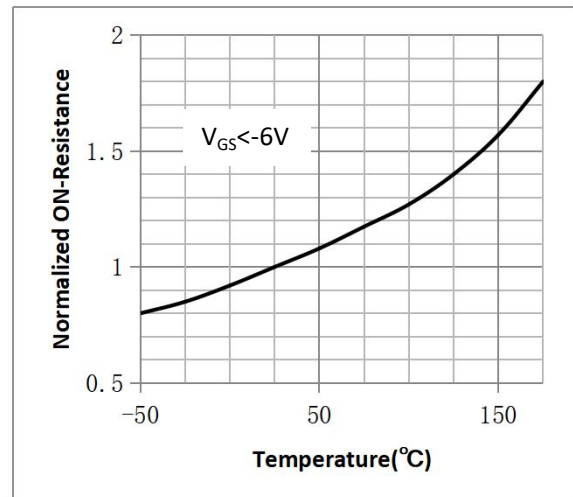


Figure 9. Diode Forward Voltage vs. Current

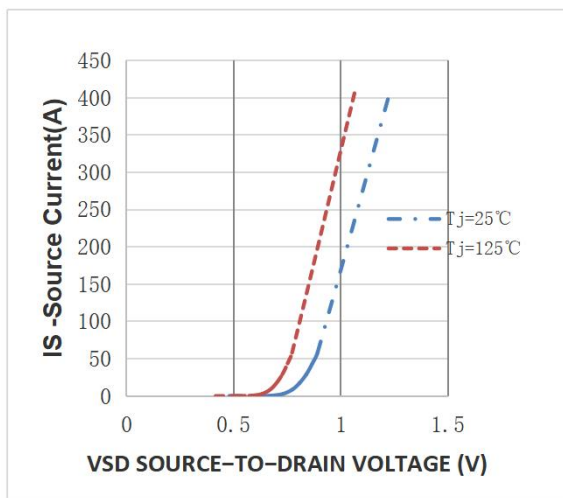


Figure 10. Transfer Characteristics

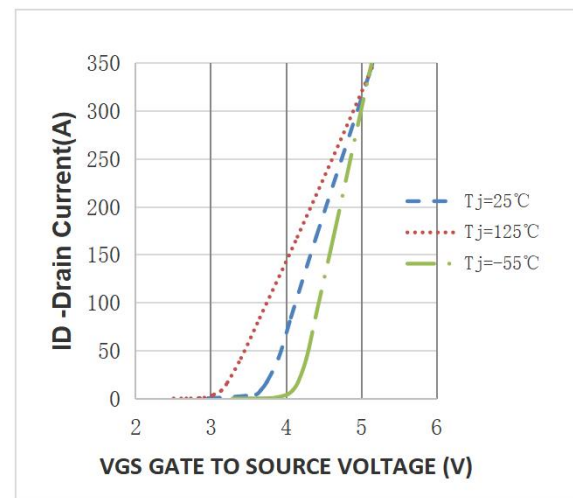


Fig.11 Safe Operating Area

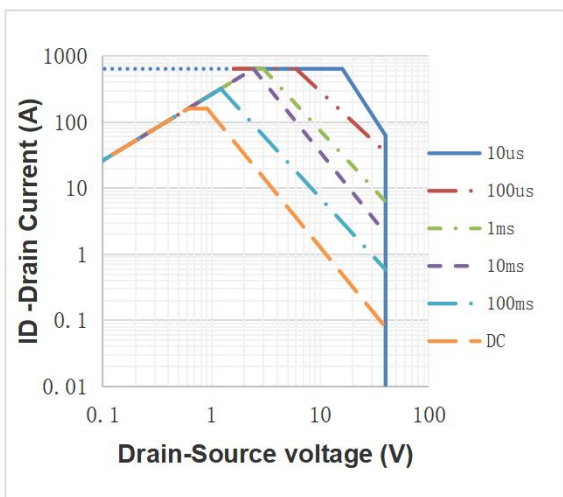
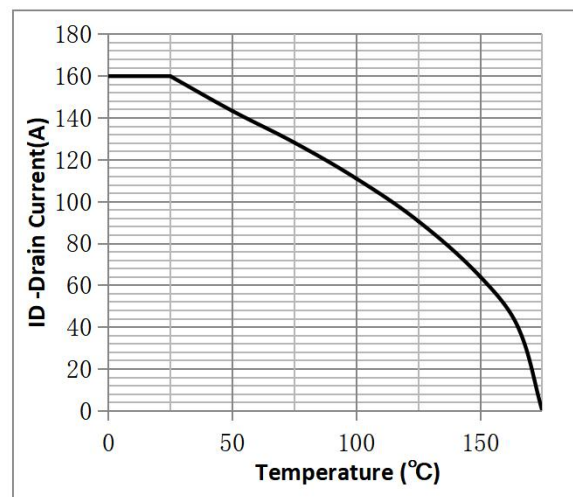
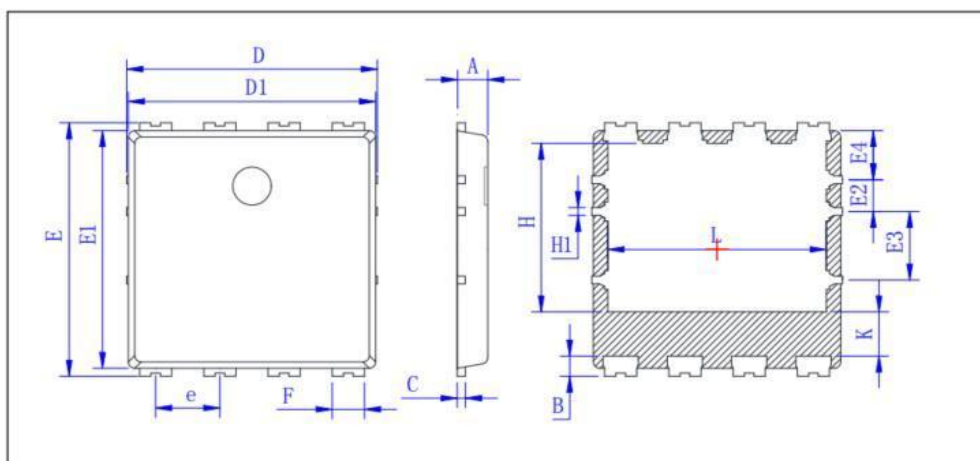


Fig.12 ID vs. Case Temperature^③



•DFN8*8 Package Outline



Symbol	Min	Typ	Max
A	0.90	0.95	1.00
B	0.50	0.60	0.70
C	0.254 TYP		
D	7.70	7.80	7.90
D1	7.60	7.70	7.80
E	7.90	8.00	8.10
E1	7.40	7.50	7.60
E2	0.90	1.00	1.10
E3	2.06	2.16	2.26
E4	1.45	1.55	1.65
e	2.0 TYP		
F	1.00 TYP		
H	5.15	5.30	5.40
H1	0.20	0.25	0.35
L	6.60	6.80	6.90
K	1.20		

Note:

- ① Pulse : VGS=+20V/-20V, Duty cycle=50%, Tj=175 °C, t=1000 hours; For DC , the following test conditions can be passed: VGS=-20V/+10V, Tj=175 °C, t=1000 hours;
- ② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;
- ③ Practically the current will be limited by PCB, thermal design and operating temperature. VGS=-10V.

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Revision History

Version	Date	Change
A	2022.11.3	NEW
B	2022.12.20	1.Modified Typical output Characteristics curve